

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT4709833

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
HWEE SENG JIMMY CHEW	11/29/2017
RECEIVING PARTY DATA	
Name:	PEP INNOVATION PTE LTD
Street Address:	BLOCK 21 KALLANG AVENUE, #02-167
City:	SINGAPORE
State/Country:	SINGAPORE
Postal Code:	339412
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15826268
CORRESPONDENCE DATA	
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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Email:	NPPATENT@NIXONPEABODY.COM
Correspondent Name:	NIXON PEABODY LLP
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Address Line 2:	SUITE 500
Address Line 4:	WASHINGTON, D.C. 20001
ATTORNEY DOCKET NUMBER:	202049-100003USPT
NAME OF SUBMITTER:	THOMAS P. PAVELKO
SIGNATURE:	/Thomas P. Pavelko/
DATE SIGNED:	11/29/2017
Total Attachments: 3	
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ASSIGNMENT

THIS ASSIGNMENT is made the 29th day of November 2017

BETWEEN

CHEW HWEE SENG, JIMMY, a citizen of Singapore, of 3A Siglap Terrace, Singapore 455829, hereinafter referred to as "the Assignor" of the one part;

AND

PEP INNOVATION PTE LTD, a company incorporated in Singapore of Block 21 Kallang Avenue, #02-167, Singapore 339412, hereinafter referred to as "the Assignee" of the other part.

WHEREAS:

- (a) The Assignor is the proprietor of the patent applications listed in Annex A (hereinafter referred to as "the Patents") and the proprietor of the inventions relating to the Patents (hereinafter referred to as "the Inventions").
- (b) The Assignee desires to acquire the entire right, title and interest in and to the Inventions and the Patents.
- (c) The Assignor has agreed to assign the Inventions and the Patents to the Assignee upon the terms and conditions set out hereunder.

NOW THIS ASSIGNMENT WITNESSETH AS FOLLOWS:

- 1. In consideration of the sum of US\$1 now paid by the Assignee to the Assignor (the receipt and sufficiency of which is hereby acknowledged), the Assignor hereby assigns absolutely to the Assignee free from encumbrances:
 - 1.1 ALL of its right title and interest in and to the Inventions and the Patents and, as of the effective date hereinafter defined, all rights and powers arising or accrued therefrom including the right to sue for damages and other remedies in respect of any infringement of such rights or other acts within the scope of the claims of any published specification of the Patents or accompanying any application therefore irrespective of whether such infringement or acts took place before or after the date of this Assignment;
 - 1.2 The right to apply for prosecute and obtain patent or similar protection throughout the world in respect of the Inventions claimed in the Patents including the right to claim priority therefrom to the intent that the grant of any patent(s) or similar protection shall be in the name of and vest in the Assignee;

TO HOLD the same unto the Assignee absolutely.

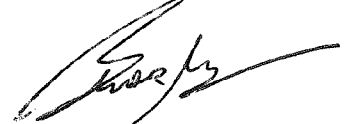
2. This Assignment is to have an effective date of 28 November 2017
3. The Assignor further covenants that at the request and cost of the Assignee, the Assignor will execute all such documents and do all such acts as may reasonably be necessary or proper to secure the vesting in the Assignee of all rights assigned hereunder.

IN WITNESS whereof this Assignment has been executed by the Assignor and a duly authorised representative on behalf of the Assignee hereto.

Signed by
CHEW HWEE SENG, JIMMY

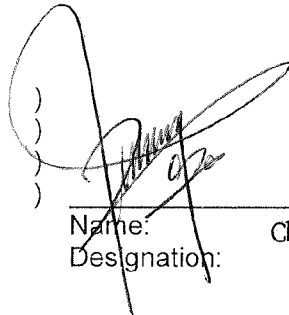
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In the presence of:-



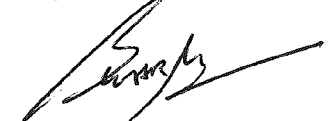
Name: *Raymond Lim*
Designation:

Signed for and on behalf of
PEP INNOVATION PTE LTD

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)
)


Name: Chew Hwee Seng, Jimmy
Designation:

In the presence of:-



Name: *Raymond Lim.*
Designation:

ANNEX A

No.	File Ref.	Country	Application No.	Filing Date	Title
1	SG6867	Singapore	10201610033Y	29 Nov 2016	SEMICONDUCTOR PACKAGE AND METHOD OF FORMING THEREOF
2	SG6868	Singapore	10201610034W	29 Nov 2016	SEMICONDUCTOR PACKAGE FOR 3D STACKING AND METHOD OF FORMING THEREOF
3	SG7087	Singapore	10201701865W	8 Mar 2017	SEMICONDUCTOR PACKAGE AND METHOD OF FORMING THEREOF

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